

HEAT-RESISTANT ADHESIVE MATERIAL

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Abstract

PURPOSE: To obtain an adhesive material having excellent electrical characteristics, chemical resistance, low water-absorptivity and high dimensional stability and useful for fixing a lead frame, etc., by laminating a specific heat- resistant adhesive to a surface of a polyphenylene sulfide resin film.

CONSTITUTION: This adhesive material is produced by coating (A) at least one surface of a polyphenylene sulfide resin film such as a film treated with corona discharge or low-temperature plasma with (B) a heat-resistant adhesive comprising a polyimide resin thin film produced by imidating a polyamic acid derived from an aromatic tetracarboxylic acid and a diamine component containing $\geq 5\text{mol\%}$ of the diamine of the formula $((n))$ is ≥ 1 ; R1 and R2 are lower alkylene or phenylene; R3 to R6 are lower alkyl, phenyl or phenoxy) as at least one of the coating layers.

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